



Material Content Data Sheet



Sales Product Name				BSC046N10NS3 G		Issued		1. August 2018	
MA#				MA001284274					
Package				PG-TDSON-8-7		Weight*		119.93 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.818	1.52	1.52	15163	15163	
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		95		
	non noble metal	iron	7439-89-6	0.038	0.03		315		
	non noble metal	copper	7440-50-8	37.762	31.48	31.52	314872	315282	
	noble metal	gold	7440-57-5	0.045	0.04	0.04	374	374	
encapsulation	organic material	carbon black	1333-86-4	0.085	0.07		709		
	plastics	epoxy resin	-	6.033	5.03		50309		
	inorganic material	silicondioxide	60676-86-0	36.370	30.33	35.43	303269	354287	
leadfinish	non noble metal	tin	7440-31-5	1.452	1.21	1.21	12104	12104	
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1380	1380	
solder	non noble metal	tin	7440-31-5	0.050	0.04		416		
	noble metal	silver	7440-22-4	0.062	0.05		519		
	non noble metal	lead	7439-92-1	2.380	1.98	2.07	19843	20778	
heatspreader	inorganic material	phosphorus	7723-14-0	0.003	0.00		28		
	non noble metal	iron	7439-89-6	0.011	0.01		95		
	non noble metal	copper	7440-50-8	11.320	9.44	9.45	94391	94514	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		56		
	non noble metal	iron	7439-89-6	0.022	0.02		186		
	non noble metal	copper	7440-50-8	22.292	18.59	18.62	185876	186118	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com